

MSKSEMI 美森科

SEMICONDUCTOR



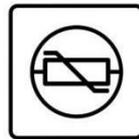
ESD



TVS



TSS



MOV



GDT



PLED

AZ5825-01F-MS

Product specification

FEATURES

- ESD per IEC 61000-4-2 ±30 kV (Contact)
- ESD per IEC 61000-4-2 ±30 kV (Air)
- IEC61000-4-4 (EFT) 40A (5/50ns)
- Peak power dissipation: 400W (8/20µs)
- Protects one Vcc or data line
- Low clamping voltage
- Working voltages : 5V
- Low leakage current
- Low capacitance

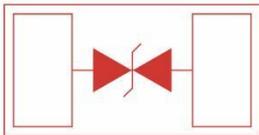
MACHANICAL DATA

- DFN100-2L package
- Flammability Rating: UL 94V-0
- High temperature soldering guaranteed: 260C/10s
- Packaging: Tape and Reel
- Reel size: 7 inch

APPLICATIONS

- Cell Phone Handsets and Accessories
- Microprocessor based equipment
- Personal Digital Assistants (PDA's)
- Notebooks, Desktops, and Servers
- Portable Instrumentation
- Networking and Telecom
- Serial and Parallel Ports
- Peripherals

Reference News

PACKAGE OUTLINE	PIN CONFIGURATION	Marking
		
<p>DFN1006-2L</p>		

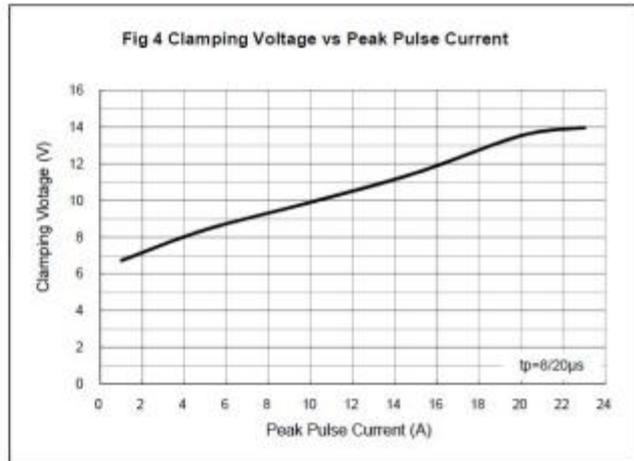
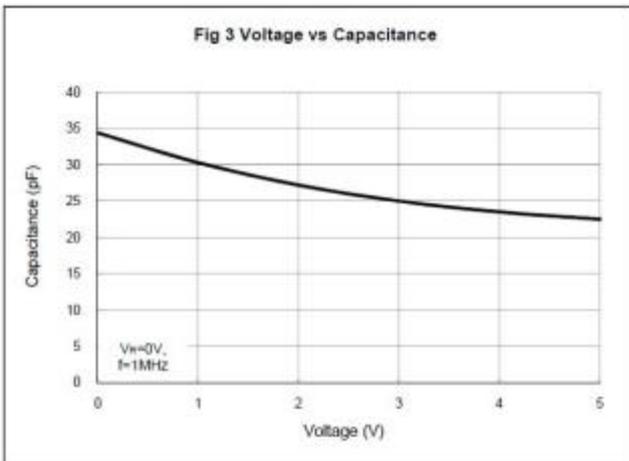
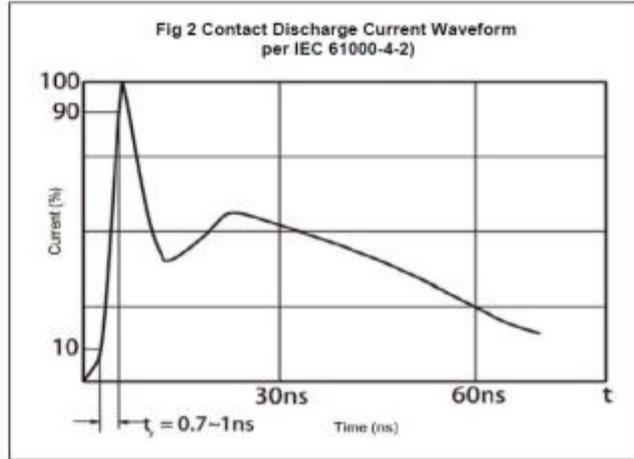
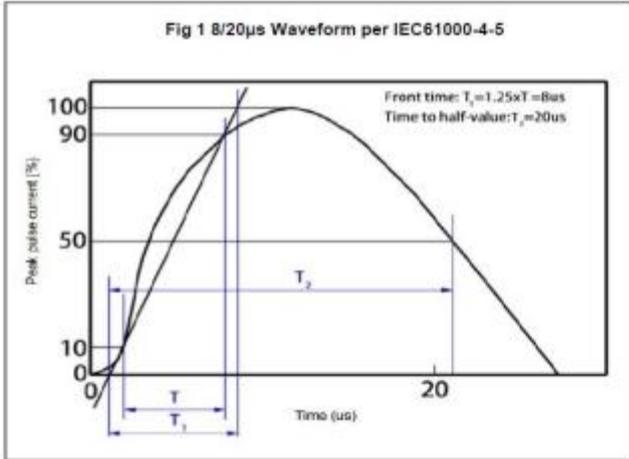
ABSOLUTE MAXIMUM RATING

Symbol	Parameter	Value	Units
VESD	ESD per IEC 61000-4-2 (Contact)	±30	kV
	ESD per IEC 61000-4-2 (Air)	±30	
PPP	Peak Pulse Power (8/20μs)	400	W
TOPT	Operating Temperature	-55~150	OC
TSTG	Storage Temperature	-55~150	OC

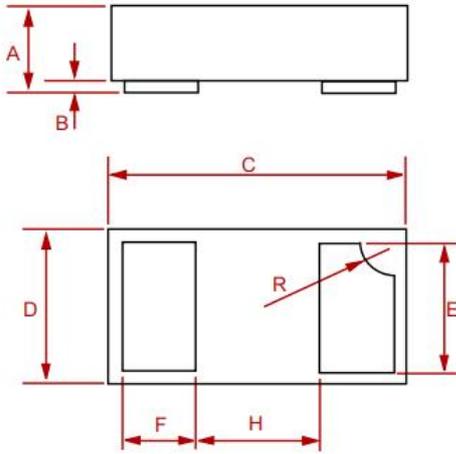
ELECTRICAL CHARACTERISTICS (Tamb=25 °C)

Symbol	Parameter	Test Condition	Min	Typ	Max	Units
VRWM	Reverse Working Voltage				5.0	V
VBR	Reverse Breakdown Voltage	IT = 1mA	5.8		9.0	V
IR	Reverse Leakage Current	VRWM = 5V			1.0	μA
VC	Clamping Voltage	I _{PP} = 1A, t _p = 8/20μs			9.8	V
VC	Clamping Voltage	I _{PP} = 20A, t _p = 8/20μs		15	20	V
CJ	Junction Capacitance	VR = 0V, f = 1MHz		33	40	pF

ELECTRICAL CHARACTERISTICS CURVE

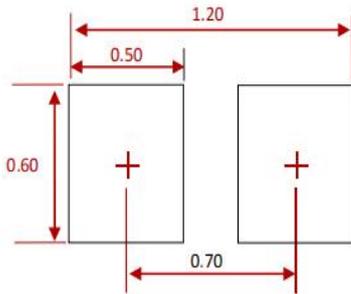


PACKAGE MECHANICAL DATA



Dim	Inches		Millimeters	
	MIN	MAX	MIN	MAX
A	0.0125	0.02	0.32	0.52
B	0.000	0.002	0.00	0.05
C	0.037	0.043	0.95	1.080
D	0.022	0.027	0.55	0.680
E	0.016	0.024	0.40	0.60
F	0.008	0.012	0.20	0.30
H	0.015Typ.		0.40Typ.	
R	0.001	0.005	0.05	0.15

Suggested Pad Layout



NOTES:

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

REEL SPECIFICATION

P/N	PKG	QTY
AZ5825-01F-MS	DFN1006-2L	10000

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